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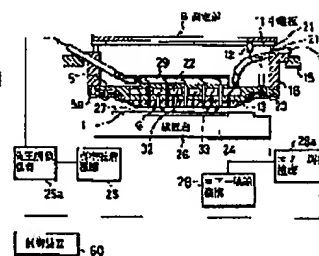
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(54) PROBE DEVICE

(57)Abstract

PURPOSE: To prevent anything other than bumps from coming into contact with the surface of a measurement object by a method wherein air is blown into a gap between a measurement object placed on a device mount and a thin film so as to correct the bending of a thin film due to the pressure of returning air.

CONSTITUTION: A probe device has such a constitution that a holding pad 23 where a thin film 13 is held is provided confronting a measurement object 1, the thin film 13 is provided to the surface of the holding pad 23 so as to face the measurement object 1, and bumps 6 provided to the thin film are brought into contact with the measurement object 1 to check the electrical properties of the object 1, wherein an air control mechanism 28a which controls so as to blow an adequate amount of air into an air gap between the surface of the measurement object 1 and thin film 1 and an air feed mechanism 28 which blows an adequate amount of air controlled by the air control mechanism 28a into the gap 27 so as to raise the pressure of the gap higher than an atmospheric pressure are provided to correct the bending of the thin film 13 by a pressure of air.



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